

3.0x2.0mm PHOTOTRANSISTOR

Part Number: AA3021P3S

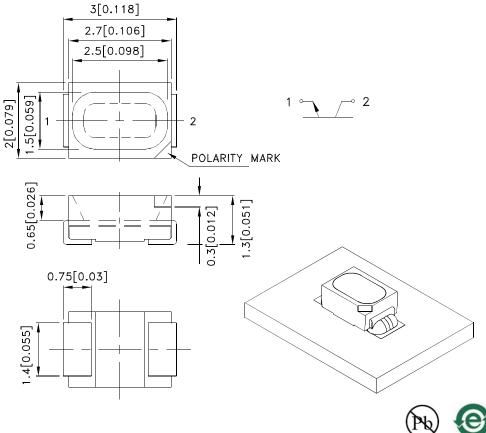
Features

- Mechanically and spectrally matched to the infrared emitting LED lamp.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

Made with NPN silicon phototransistor chips.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

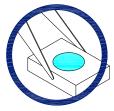
REV NO: V.4 SPEC NO: DSAM1638 DATE: SEP/29/2016 PAGE: 1 OF 5 APPROVED: Wynec **CHECKED: Allen Liu** ERP: 1201007031 DRAWN: L.T.Zhang

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

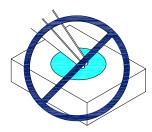
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

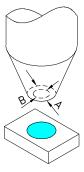




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

 SPEC NO: DSAM1638
 REV NO: V.4
 DATE: SEP/29/2016
 PAGE: 2 OF 5

 APPROVED: Wynec
 CHECKED: Allen Liu
 DRAWN: L.T.Zhang
 ERP: 1201007031

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100uA Ee=0mW/cm ²
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	IE=100uA Ee=0mW/cm ²
VCE (SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	Ic=2mA Ee=20mW/cm ²
I CEO	Collector Dark Current			100	nA	VcE=10V Ee=0mW/cm ²
TR	Rise Time (10% to 90%)		15		us	VcE = 5V Ic=1mA RL=1000Ω
TF	Fall Time (90% to 10%)		15		us	
I (ON)	On State Collector Current	0.2	0.35		mA	$VCE = 5V$ $Ee=1mW/cm^2$ $\lambda=940nm$
λ0.1	Range of spectral bandwidth	420		1120	nm	
λр	Wavelength of peak sensitivity		940		nm	
201/2	Angle of half sensitivity		120		deg	

Absolute Maximum Ratings at TA=25°C

Parameter	Max.Ratings		
Collector-to-Emitter Voltage	30V		
Emitter-to-Collector Voltage	5V		
Power Dissipation at (or below) 25°C Free Air Temperature	100mW		
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

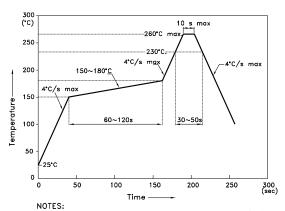
SPEC NO: DSAM1638 REV NO: V.4 DATE: SEP/29/2016 PAGE: 3 OF 5
APPROVED: Wynec CHECKED: Allen Liu DRAWN: L.T.Zhang ERP: 1201007031

^{1.} Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

AA3021P3S

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

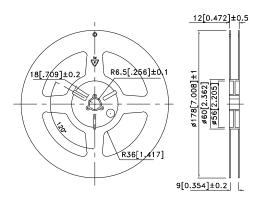
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

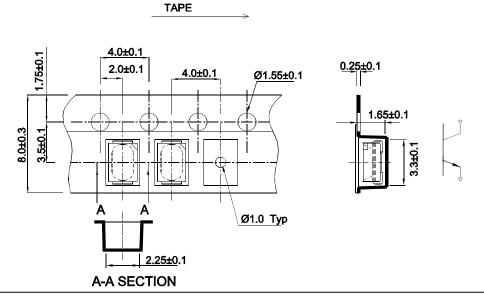
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

1.4 ...

Tape Specifications (Units : mm)

Reel Dimension



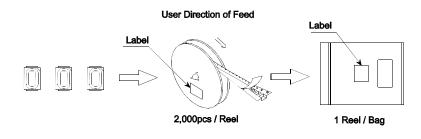


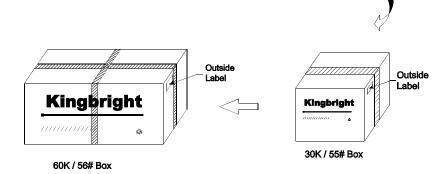
SPEC NO: DSAM1638
APPROVED: Wynec

REV NO: V.4 CHECKED: Allen Liu DATE: SEP/29/2016 DRAWN: L.T.Zhang PAGE: 4 OF 5 ERP: 1201007031

PACKING & LABEL SPECIFICATIONS

AA3021P3S







Terms and conditions for the usage of this document

- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- 5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- 6. All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

SPEC NO: DSAM1638 REV NO: V.4 DATE: SEP/29/2016 PAGE: 5 OF 5
APPROVED: Wynec CHECKED: Allen Liu DRAWN: L.T.Zhang ERP: 1201007031